

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	541	257/706.ccls. and (heat adj (sink slug element spreader plate radiation)) and (mold\$4 encapsula\$4 packag\$4) and (insulat\$4 dielectric)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 12:33
L2	342	L1 and @ad<="20010702"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 12:33
L3	1294	257/712-718.ccls. and (heat adj (sink slug element spreader plate radiation)) and (mold\$4 encapsula\$4 packag\$4) and (insulat\$4 dielectric)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 12:33
L4	951	L3 and @ad<="20010702"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 12:33
L5	774	L4 not L2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 15:58
L8	1	(encapsulation encapsulant encapsulating sealing sealant seal molding mold\$2) with (lead support paddle) with (expos\$3 protrud\$3) with (second adj length)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 16:05
L9	338	(encapsulation encapsulant encapsulating sealing sealant seal molding mold\$2) with (lead support paddle) with (expos\$3 protrud\$3) with length	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 16:56
L10	117	9 and (chip die IC (integrated adj circuit))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 16:09
L11	2	("6611011").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/09 16:10

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L12	2	("6611001").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/09 16:10
L14	3	(molding adj line) with (lead support paddle) with (expos\$3 protrud\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 16:57
L15	2412	((encapsulation encapsulant encapsulating sealing sealant seal molding mold\$2) with (lead support paddle) with (expos\$3 protrud\$3)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 16:59
L16	127	((encapsulation encapsulant encapsulating sealing sealant seal molding mold\$2) with (lead support paddle) with (expos\$3 protrud\$3) same length).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 17:13
L17	0	16 not 15	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 16:58
L18	0	((mold\$3 adj line) with (lead support paddle) with (expos\$3 protrud\$3)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 16:59
L19	10	(mold\$3 adj line) with (lead support paddle) with (expos\$3 protrud\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 17:01
L21	1237	((encapsulation encapsulant encapsulating sealing sealant seal molding mold\$2) with (lead support paddle) with (expos\$3 protrud\$3) with (length surface)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 17:08
L22	791	21 and (chip die IC (integrated adj circuit))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 17:15

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L23	709	22 and second	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 17:10
L24	50	amano-kenji.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 17:30
L30	7	("5294827" "5521429" "5841187" "5844307" "5900676" "5973388" "5977613").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/09 17:19
L31	181	fujisawa-atsushi.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 17:33
L32	29	hasebe-hajime.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 17:33
L34	61	(encapsulation encapsulant encapsulating sealing sealant seal molding mold\$2) with (lead support paddle) with (expos\$3 protrud\$3) same length and 257/666-670.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 17:39
L35	37	(encapsulation encapsulant encapsulating sealing sealant seal molding mold\$2) with (lead support paddle) with (expos\$3 protrud\$3) same length and 257/672,674,676,678.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 17:41
L36	34	(encapsulation encapsulant encapsulating sealing sealant seal molding mold\$2) with (lead support paddle) with (expos\$3 protrud\$3) same length and 257/690-693.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 17:44

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L37	54	("20040036180" "3838984" "4159221" "4398235" "4833568" "4956694" "4996587" "5068713" "5230759" "5258094" "5266834" "5332864" "5381039" "5381047" "5394010" "5414300" "5435057" "5455387" "5521429" "5581118" "5587341" "5594275" "5625221" "5677569" "5715147" "5742007" "5760471" "5835988" "5852320" "5859471" "5877043" "5880403" "5950074" "5962810" "5977613" "5986209" "6114221" "6130115" "6143981" "6180881" "6225146" "6235554" "6242281" "6281568" "6320251" "6356453" "6404046" "6433418" "6459148" "6518659" "6564454" "6577013" "6646339" "6730544").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/09 17:42
L38	29	(encapsulation encapsulant encapsulating sealing sealant seal molding mold\$2) with (lead support paddle) with (expos\$3 protrud\$3) same length and 257/787-788.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 17:44